



Material Content Data Sheet



Halogen-Free

Sales Product Name IPBE65R230CFD7A

Issued

24. February 2022

MA# MA005708553

Package PG-TO263-7-11

Weight*

1555.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.951	0.25	0.25	2541	2541
leadframe	inorganic material	phosphorus	7723-14-0	0.257	0.02		165	
	non noble metal	iron	7439-89-6	0.856	0.06		550	
	non noble metal	copper	7440-50-8	854.720	54.97	55.05	549639	550354
wire	non noble metal	aluminium	7429-90-5	3.646	0.23	0.23	2344	2344
encapsulation	inorganic material	zinc oxide	1314-13-2	5.715	0.37		3675	
	miscellaneous	miscellaneous	-	22.861	1.47		14701	
	plastics	epoxy resin	-	85.729	5.51		55130	
	inorganic material	silicon dioxide	60676-86-0	457.224	29.40	36.75	294024	367530
lead finish	non noble metal	tin	7440-31-5	9.890	0.64	0.64	6360	6360
plating	inorganic material	phosphorus	7723-14-0	0.010			7	
	non noble metal	nickel	7440-02-0	4.272	0.27	0.27	2747	2754
solder	non noble metal	tin	7440-31-5	0.068			44	
	noble metal	silver	7440-22-4	0.085	0.01		55	
	non noble metal	lead	7439-92-1	3.261	0.21	0.22	2097	2196
heatspreader	inorganic material	phosphorus	7723-14-0	0.031			20	
	non noble metal	iron	7439-89-6	0.103	0.01		66	
	non noble metal	copper	7440-50-8	102.377	6.58	6.59	65835	65921
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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